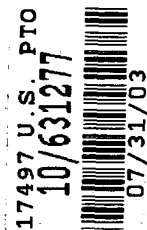


**SIEMENS**

Express Mail Label No.: EV 339090155US

**UTILITY PATENT**

Case Docket No.: 2003P10694US



Mail Stop PATENT APPLICATION  
 Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Date: July 31, 2003

Date of Deposit: July 31, 2003

Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s): Jay Alan Morrison  
 Gary Brian Merrill

For (title): BOND ENHANCEMENT FOR THERMALLY INSULATED CERAMIC  
 MATRIX COMPOSITE MATERIALS

This application includes:

18 pages: specification, claims, and abstract  
6 sheets of drawings containing 13 figures

Also enclosed is:

- ☒ Declaration and Power of Attorney  
☒ An assignment of the invention to Siemens Westinghouse Power Corporation  
☐ A certified copy of a \_\_\_\_\_ application.  
☒ Information Disclosure Statement pursuant to 37 CFR 1.56.

The filing fee has been calculated as shown below:

					FEE
BASIC FEE OTHER THAN SMALL ENTITY					\$ 750
TOTAL CLAIMS		EXTRA			
<u>24</u> - 20	=	<u>4</u>	x \$18.00	=	\$ <u>72</u>
INDEP CLAIMS					
<u>4</u> - 3	=	<u>1</u>	x \$84.00	=	\$ <u>84</u>
*MULTIPLE DEPENDENT CLAIM PRESENTED + \$72					= \$ <u>0</u>
TOTAL					\$ 906

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X Any filing fees under 37 CFR 1.16 for presentation of extra claims.

All correspondence related to this application should be sent to:

Siemens Corporation  
Intellectual Property Department  
170 Wood Avenue South  
Iselin, NJ 08830  
Tel. (732) 321-3026

Dated: July 31, 2003



David G. Maire  
Registration No. 34,865  
(407)-926-7704

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of )  
Applicants: Jay Alan Morrison, et al )  
Application No.: Not Assigned )  
Filing Date: Simultaneously Herewith )  
For: BOND ENHANCEMENT FOR THERMALLY )  
INSULATED CERAMIC MATRIX )  
COMPOSITE MATERIALS )

Attorney Docket: 2003P10694US

Mail Stop Patent Application  
Commissioner for Patents  
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Sir:

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Date of Deposit: July 31, 2003

I hereby certify that the attached patent application, formal papers, and drawings were deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to: Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Respectfully submitted,



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